

## **Tera Probe Acquires Wafer Bump Facilities from Fujitsu Semiconductor and Starts Accepting Orders**

**Yokohama, Japan, November 28, 2013**

Tera Probe today announced that it has acquired ownership of Fujitsu Semiconductor's 300mm wafer bump facilities and has started to accept business orders processed by these facilities.

**1. Reason for the transfer of the wafer bump facilities to Tera Probe and the start of business orders**

Tera Probe believes that the acquisition of the Fujitsu Semiconductor's 300mm wafer bump facilities and the processing of orders using these facilities is an effective way for the Tera Probe group to develop new customers and strengthen its business. The acquisition should also help boost corporate value.

**2. Business handled by the acquired facilities and related business orders**

Fujitsu Semiconductor's 300mm wafer bump facilities and bumping-related business orders processed through these facilities.

**3. Overview of Fujitsu Semiconductor**

(1)	Company name	Fujitsu Semiconductor Ltd.
(2)	Location	2-10-23 Shin-Yokohama, Kohoku-Ku, Yokohama, Kanagawa Prefecture
(3)	Company president	Mr. Haruki Okada
(4)	Business	LSI design, development, manufacturing and sales
(5)	Capital	60 billion yen
(6)	Established	March 21, 2008

**4. Outlook**

The acquisition of Fujitsu Semiconductor's wafer bump facilities and the processing of orders through these facilities are expected to have a minimal impact on Tera Probe's consolidated business.

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